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 UNITED STATES PATENT AND TRADEMARK OFFICE
 WASHINGTON, D.C. 20231
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APPLICATION NUMBER	FILING/RECEIPT DATE	FIRST NAMED APPLICANT	ATTORNEY DOCKET NUMBER
10/023,723	12/21/2001	Biju Chandran	219.40780X00

CONFIRMATION NO. 5137

FORMALITIES LETTER



OC000000007517919

 020457
 ANTONELLI TERRY STOUT AND KRAUS
 SUITE 1800
 1300 NORTH SEVENTEENTH STREET
 ARLINGTON, VA 22209

Date Mailed: 02/22/2002

NOTICE TO FILE MISSING PARTS OF NONPROVISIONAL APPLICATION

FILED UNDER 37 CFR 1.53(b)

Filing Date Granted

An application number and filing date have been accorded to this application. The item(s) indicated below, however, are missing. Applicant is given **TWO MONTHS** from the date of this Notice within which to file all required items and pay any fees required below to avoid abandonment. Extensions of time may be obtained by filing a petition accompanied by the extension fee under the provisions of 37 CFR 1.136(a).

- The oath or declaration is missing.
A properly signed oath or declaration in compliance with 37 CFR 1.63, identifying the application by the above Application Number and Filing Date, is required.
- To avoid abandonment, a late filing fee or oath or declaration surcharge as set forth in 37 CFR 1.16(l) of \$130 for a non-small entity, must be submitted with the missing items identified in this letter.
- The balance due by applicant is \$ 130.

05/09/2002 UTRUONG1 00000013 012135 10023723

01 FC:105 65.00 CH 65.00 OP

A copy of this notice **MUST** be returned with the reply.

Customer Service Center

Initial Patent Examination Division (703) 308-1202

PART 2 - COPY TO BE RETURNED WITH RESPONSE

04/19/2002 CNGUYEN 00000070 10023723

01 FC:205 65.00 OP

Adjustment date: 05/09/2002 UTRUONG1

04/19/2002 CNGUYEN 00000070 10023723

01 FC:205 65.00 OP



219.40780X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: B. CHANDRAN ET AL.
Serial No.: 10/023,723
Filing Date: December 21, 2001
For: SEMICONDUCTOR PACKAGE WITH LOW RESISTANCE
PACKAGE-TO-DIE INTERCONNECT SCHEME FOR
REDUCED DIE STRESSES

ATTENTION: Customer Service Center
Initial Patent Examination Division

**RESPONSE TO NOTICE TO FILE MISSING PARTS
OF APPLICATION - SUBMISSION OF LATE DECLARATION**

Assistant Commissioner for Patents
Washington, D. C. 20231

April 18, 2002

Sir:

In response to the Notice to File Missing Parts of Application mailed February 22, 2002 in connection with the above-identified application, Applicants are filing herewith an executed Declaration for patent application in compliance with 37 C.F.R. §1.63. In addition, Applicants are also submitting a Credit Card Payment Form for \$65.00 (small entity) to cover the surcharge for the filing of the belated Declaration in accordance with 37 C.F.R. §1.16(e).

To the extent necessary, Applicants petition for an extension of time under 37 C.F.R. §1.136. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 01-2135 (219.40780X00) and please credit any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP



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